

N-Channel 150-V (D-S) MOSFET

Description

The device is using trench DMOS technology. This advanced technology has been especially tailored to minimize $R_{DS(ON)}$, provide superior switching performance, and withstand high energy pulse in the avalanche and commutation mode. These devices are well suited for high efficiency fast switching applications.

The device meets the RoHS and Green Product requirement, 100% EAS guaranteed with full function reliability approved.

Features

- $R_{DS(ON)} = 9.0 \text{m}\Omega @ V_{GS} = 10V$
- Super Low Gate Charge
- Excellent dv/dt Capability
- 100% EAS Guaranteed
- Green Device Available

Typical Applications

- Networking
- Load Switch
- Synchronous Rectifier
- Quick Charger

Package type: TO-220

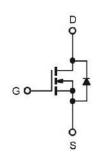
Packing & Order Information

2,000/Box

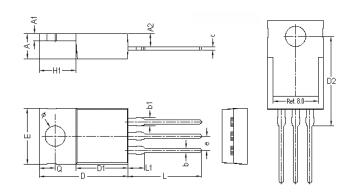


RoHS Compliant

Graphic Symbol

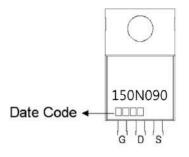


Package Dimension



REF.	Millimeter		REF.	Millimeter		
	Min.	Max.	INEI.	Min.	Max.	
Α	4.30	4.70	D2	15.70	17.00	
A1	1.20	1.40	Е	9.70	10.36	
A2	2.30	2.79	е	2.54 BSC		
b	0.70	0.90	H1	6.10	6.70	
b1	1.20	1.75	L	12.80	13.90	
С	0.34	0.60	L1	-	4.00	
D	14.70	16.10	Q	2.60	3.00	
D1	8.60	9.30	Ø	3.55	3.95	

Marking





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MAXIMUM RATINGS AND ELECTRICAL CHARACTERISTICS

Absolute Maximum Ratings					
Symbol	Parameter	Value	Units		
V _{DS}	Drain-Source Voltage	150	V		
V _G S	Gate-Source Voltage	±20	V		
I _D	Continuous Drain Current¹ (Tc =25°C)	100	Α		
	Continuous Drain Current¹ (Tc=100°C)	63	A		
I _{DM}	Pulsed Drain Current ^{1,2}	400	Α		
las	Single Pulse Avalanche Current, L =0.5mH³	56	Α		
Eas	Single Pulse Avalanche Energy, L =0.5mH³	784	mJ		
P _D	Power Dissipation ⁴ (T _C =25°C)	178	W		
T _J /T _{STG}	Operating Junction and Storage Temperature	-55 to 150	°C		

Thermal Resistance Ratings					
Symbol	Parameter	Maximum	Units		
$R_{\theta JA}$	Maximum Junction-to-Ambient ¹	50	°C/W		
$R_{ heta JC}$	Maximum Junction-to-Case ¹	0.7	°C/W		

Electrical Characteristics (T」=25°C unless otherwise specified)							
Symbol	Parameter	Test Conditions	Min.	Тур.	Max.	Units	
$V_{\text{GS (th)}}$	Gate Threshold Voltage	V _{DS} =V _{GS} , I _D =250μA	2	3	4	V	
BV _{DSS}	Drain-Source Breakdown Voltage	V _{GS} =0V, I _D =250μA	150	-	-	V	
I _{GSS}	Gate-Source Leakage Current	V _{DS} =0V, V _{GS} =±20V	-	-	±100	nA	
I _{DSS}	Drain-Source Leakage Current	V _{DS} =120V, V _{GS} =0V, T _J =25°C V _{DS} =120V, V _{GS} =0V, T _J =55°C	-	-	1 5	μA	
R _{DS} (on)	Static Drain-Source On-Resistance ²	V _{GS} =10V, I _D =20A	-	7.3	9.0	mΩ	
Rg	Gate Resistance	VDS=0V , VGS=0V , f=1MHz	-	1.9	-	Ω	
EAS	Single Pulse Avalanche Energy ⁵	V _{DD} =50V, L =0.5mH, I _{AS} =30A	225	-	-	mJ	
V _{SD}	Diode Forward Voltage ²	I _S =1A, V _{GS} =0V, T _J =25°C	-	-	1.2	V	
Is	Continuous Source Current ^{1,6}	V V 0V 5	-	-	100		
Ism	Pulsed Source Current ^{2,6}	V _G =V _D =0V, Force Current	-	-	300	Α	

Notes

- 1. The data tested by surface mounted on a 1 inch² FR-4 board with 2OZ copper.
- 2. The data tested by pulsed, pulse width \leq 300us, duty cycle \leq 2%.
- 3. The EAS data shows maximum rating. The test condition is V_{DD} =50, V_{GS} =10V, L=0.5mH, I_{AS} =56A.
- 4. The power dissipation is limited by 150 $^{\circ}$ C junction temperature.
- 5. The Min. value is 100% EAS tested guarantee.
- 6. The data is theoretically the same as I_D and I_{DM} , in real applications, should be limited by total power dissipation.



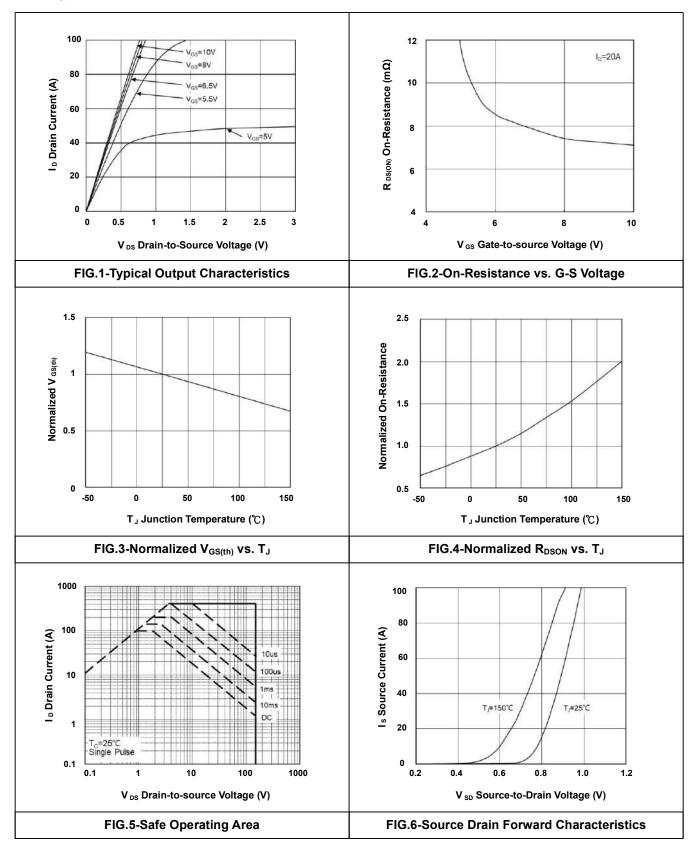
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Dynamic							
Symbol	Parameter	Test Conditions	Min.	Тур.	Max.	Units	
Qg	Total Gate Charge ²	V _{DS} =75V		100			
Qgs	Gate-Source Charge	I _D =20A		25		nC	
Qgd	Gate-Drain Charge	V _{GS} =10V		31			
td(on)	Turn-On Delay Time ²	V _{DS} =30V		32			
tr	Rise Time	I _D =1A		25			
td(off)	Turn-Off Delay Time	V _{GS} =10V		97		ns	
tf	Fall Time	R _G =3.3Ω		89			
Ciss	Input Capacitance	V _{DS} =75V		5870			
Coss	Output Capacitance	V _{GS} =0V		404		pF	
Crss	Reverse Transfer Capacitance	f =1.0MHz		9.3		1	



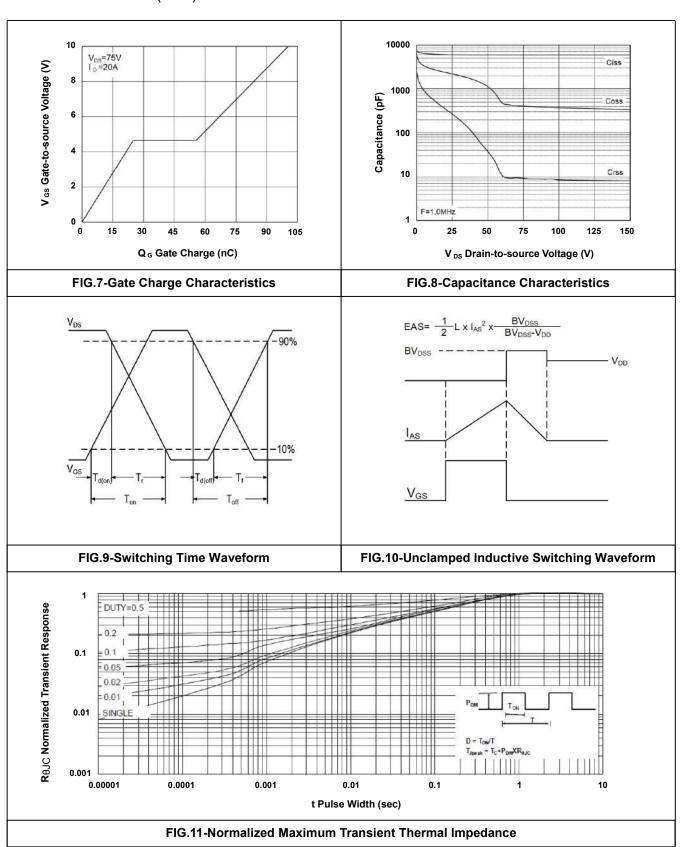
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• Typical Electrical Characteristics





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